+44 20 8123 2220
info@marketpublishers.com

Global and China IC Advanced Packaging Equipment Industry Report, 2013-2014

https://marketpublishers.com/r/G4BAD1EA884EN.html
Date: August 2014
Pages: 120
Price: US$ 2,300.00 (Single User License)
ID: G4BAD1EA884EN

Abstracts

Global and China IC Advanced Packaging Equipment Industry Report, 2013-2014 mainly deals with the followings:

1. Overview of semiconductor industry
2. Status quo of memory and wafer foundry industry
3. Downstream market of semiconductor industry
4. Trend in emerging advanced packaging technology
5. Packaging equipment industry analysis and ranking
6. 15 major advanced packaging equipment vendors

Packaging equipment can fall into two categories: wafer level and die level. And the former is typically included in wafer equipment as it is used in the manufacturing of wafer. Wafer level packaging is primarily used in the following 5 fields, namely, Analog & Mixed Signal (including IPD, PA, PMU, Local Power, IC Driver, and Audio & Video), Wireless Connectivity (including Bluetooth+FM+WLAN Combo and GPS Single Chip), Optoelectronic (including CIS, AL Sensor), MEMS & Sensor (including Accelerometers, Gyroscope, RF-MEMS, Pressure Sensor, and Fingerprint Sensor), as well as Misc Logic and Memory (covering Logic gate and EEPROMs). And these applications mostly adopt the Fan-in design, with the number of Pin usually less than 20.

In future, WLCSP will be required to follow the Fan-out design to expand its applications. However, the current Fan-out design, which is not mature, restricts the application of wafer level packaging, leaving an untapped market potential for now. But if the Fan-out design is mature, WLCSP will embark on a new development stage.

Wafer level packaging equipment consists of Process Tool (mainly including CVD and

PVD, Etching, Sputtering), Packaging Lithography, Contact Probers, and Packaging Inspection. Among them, the main vendors of Process Tool are Applied Material (including the acquired NEXX) and ULVAC; the major companies in Packaging Lithography field are Ultratech, SUSS, and EV Group; the companies involved in Contact Probers are represented by Tokyo Seimitsu and Tokyo Electron(already acquired by Applied Material); the companies engaging in Packaging Inspection principally include Rudolph, Camtek, and KLA-TENCOR. In 2014, the market size of wafer packaging level equipment will be very likely to reach approximately USD1.3 billion.

Die packaging level equipment mainly involves Wire Bonder (main vendors are Kulicke & Soffa, ASM Pacific, and Shinkawa), Die Bonder (represented by ASM Pacific, Hitachi High Technologies, BESI, and Canon), Flip chip Bonder (typical vendors cover PFSA, BESI, ASM Pacific, Toray Engineering, and Hanmi), Test Handler (Delta Design, Advantest, Epson, and Tesec serve as the major players), Wafer Dicing Saws (players include DISCO and Tokyo Seimitsu), Molding/Encapsulation (Towa, BESI, Dai-ichi Seiko are the typical vendors), and Package singulation (Hanmi, ASM Pacific, and DISCO play the main role).

With obvious periodicity, semiconductor devices saw a rise during 2001-2007 but a slump in 2008-2009, while fiercely surged by 100% in 2011, then declined for 3 consecutive years from 2011. And in 2014, they will witness an explosive growth, with the estimated market size of die packaging level equipment rising significantly by 20% to USD4.1 billion. And this figure is projected to climb to USD4.3 billion in 2015 and then begin to fall in 2016. The major growth engine would be Die Bonder, Flip-chip Bonder, and Test Handler.

+44 20 8123 2220
info@marketpublishers.com

Contents

Selected Charts

SELECTED CHARTS

Semiconductor Industry Growth versus Worldwide GDP Growth, 1990-2014
Quarterly Revenue of Global Semiconductor Industry, 2012-2014
Breakdown of Global Semiconductor Market by Product, 2012-2018E
Semiconductor Outsourced Supply Chain
Semiconductor Company Systems
Semiconductor Outsourced Supply Chain Example
Top 25 Semiconductor Sales Leaders, 1Q2014
Worldwide IC Sales by Company Headquarters Location, 1990-2013
Fabless IC Sales Market Share by Company Headquarters Location (77.9B), 2013
Top 10 IC Manufacturers in China, 2008-2013
Top 10 Spenders Capital Spending Outlook, 2011-2014F
Top 5 Share of Total Semiconductor Capital Spending, 1994-2013
Worldwide Semiconductor Capital Spending Share of Full Year Budget, 1Q2014
Market Size of Global DRAM and NAND, 2008-2016E
DRAM Supply/Demand, 1Q2012-4Q2014
CAPEX of DRAM Industry, 2005-2015E
ASP of 4Gb DDR3, 2012-2014
ASP of 32Gb MLC NAND, 2012-2014
Ranking of Branded DRAM Vendors by Revenue, 2Q2013-1Q2014
Market Share of DRAM, Q12007-Q12014
Market Share of Mobile DRAM, 2009-2011
Market Share of Mobile DRAM, 2012
Ranking of Branded Mobile DRAM Vendors by Revenue, 2Q2013-1Q2014
Market Share of Branded NAND Flash Vendors, 2012
Market Share of Branded NAND Flash Vendors, 2014Q1
NAND Supply/Demand, 1Q2012-4Q2014
NAND Tech Migration Roadmap
Market Size of Global Foundry, 2008-2017E
Foundry Revenue of Advanced Nodes, 2012-2017E
Global Foundry Capacity by Node, 2012-2018E
Global Foundry Revenue by Node, 2012-2018E
Global Ranking by Foundry
Average IC Costs of Each Mobile Phone, 2008-2016E
Shipments of Global Mobile Phones, 2007-2015E
Worldwide Smartphone Sales to End Users by Vendor in 2013

+44 20 8123 2220
info@marketpublishers.com

Worldwide Smartphone Sales to End Users by Operating System, 2013
Worldwide Mobile Phone Sales to End Users by Vendor, 2013
Shipments of Global CPU and Discrete GPU for PC, 2008-2015E
Shipments of NB PC, 2008-2015E
Shipments of Global NB PC ODM Vendors, 2010-2013
Shipments of Global Tablet PC, 2011-2016E
Market Share of Major Tablet PC Brands, 2013
Output of Global Tablet PC Vendors, 2012-2013
MFPGA and CPLD Markets by Application and by Region, 2011
Market Share of Major FPGA Vendors, 1999-2013
Mobile DRAM Trend
Strengths of WIDE IO
SK Hynix WIDE IO2 Roadmap
HMC Architecture
HMC BENEFITS
Advantages of Embedded Passive/Active Substrate
Embedded Component Substrate Process
Comparison of Embedded Active & Passive Components
Roadmap of Embedded Passive Substrate
Structure Roadmap of Embedded Active Substrate
FOWLP and PLP Process Comparison
WHY Embedded Trace?
Embedded Trace Package Features
Embedded Trace Package Sweet Spot (for Wire Bonding)
Embedded Trace Package Sweet Spot (for FLIP CHIP)
Apple iPad 4 LTE A1459 IC Package Type List
Trend in PoP Packaging
Market Share of Major SiP Packaging Vendors, 2014
Sales and Operation Margin of Murata, FY 2009-FY 2014
Sales of Murata by Region, FY 2009-FY 2014
Revenue, New Orders and Backlog of Murata, 2011Q1-2014Q2
Operating Income and Net Income of Murata, 2011Q1-2014Q2
Order of Murata by Product, 2011Q1-2014Q2
Sales of Murata by Product, FY 2010-FY 2014
Murata Sales by Application, FY 2010-FY 2014
Revenue and Gross Margin of USI (Taiwan), 2008-2014
Quarterly Revenue and Gross Margin of USI (Taiwan), 2013Q1-2014Q2
Quarterly Revenue Breakdown of USI (Taiwan) by Product, 2013Q1-2014Q2
Revenue and Operating Income of USI (Shanghai), 2008-2014

Revenue Operation MarginNet Margin of BESI, 2009-2014
Quarterly Revenue and Orders of BESI, 1Q2012-2Q2014
Quarterly Revenue and Net Margin of BESI, 1Q2012-2Q2014
Milestone of BESI
Quarterly Expense of BESI, 1Q12-2Q14
Quarterly Headcount of BESI, 1Q12-2Q14
Quarterly Cash and Debt of BESI, 1Q12-2Q14
Market Share of BESI, 2013
Revenue Breakdown of BESI by Product, 2013
BESI’s Product Position
BESI’s Products
BESI’s Global Operation
Revenue and Gross Margin of Advantest, 2Q12-2Q14
New Orders of Advantest, 2Q12-2Q14
Advantest Order by Business, FY 2013-Q1/FY 2015
Advantest Order by Region, FY 2013-Q1/FY 2015
Sales of Advantest by Business, FY 2013-Q1/FY 2015
Sales of Advantest by Region, FY 2013-Q1/FY 2015
Assets and Liabilities of Advantest, 2013Q3-2014Q2
Revenue and Operation Margin of Hitachi High-Technologies, FY 2007-FY 2015
Revenue Breakdown of Hitachi High-Technologies by Segment, FY 2011-FY 2015
Operation Margin Breakdown of Hitachi High-Technologies by Segment, FY 2011-FY 2014
Revenue Breakdown of Hitachi High-Technologies’ Electronic Device Systems by Business, FY 2013-FY 2015
Front-end Revenue Breakdown of Hitachi High-Technologies’ Electronic Device Systems by Field, FY 2014-FY 2015
Revenue and Operating Income of Teradyne, 2006-2014
Net Revenue of Teradyne by Country and % of Total Revenue, 2011-2013
Revenue Breakdown of Teradyne by Product, 2011-2014
Organization Chart of DISCO
Revenue and Operating Income of DISCO, FY 2010-FY 2015
Quarterly Consolidated Financial Results of DISCO, Q1/FY 2005-Q4/FY 2013
Quarterly Sales/Orders of DISCO, Q1/FY 2005-Q4/FY 2013
Quarterly Sales Breakdown of DISCO by Product, Q1/FY 2010-Q4/FY 2013
Product and Equipment Sales Breakdown, Q4/FY 2013
Equipment, Non-consolidated Cutting and Dicing Saws Sales Breakdown of DISCO by Application, FY 2012-FY 2013
Equipment, Non-consolidated Grinders and Polishers Sales Breakdown of DISCO by

I would like to order

Product name: Global and China IC Advanced Packaging Equipment Industry Report, 2013-2014

Product link: https://marketpublishers.com/r/G4BAD1EA884EN.html

Price: US$ 2,300.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page https://marketpublishers.com/r/G4BAD1EA884EN.html

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:

Last name:

Email:

Company:

Address:

City:

Zip code:

Country:

Tel:

Fax:

Your message:

**All fields are required

Custumer signature ____

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at https://marketpublishers.com/docs/terms.html

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970